

Abstract of the Disclosure:

RESIN-MOLDED UNIT INCLUDING
AN ELECTRONIC CIRCUIT COMPONENT

A resin-molded unit (1) includes a semiconductor bear chip (2) arranged inside and sealed in an epoxy resin mold (3). The resin-molded unit is entirely covered with a magnetic loss film (5) as a high-frequency current suppressor. It is preferable that the magnetic loss film is made of a granular magnetic material. A plurality of lead frames (4) may be extended from the semiconductor bear chip to the outside through the epoxy resin mold.

Figure 1